RoHS Certificate Of Compliance

Product Number	Effective Date
815 (Single port 8 Gbps FC)	10/31/11
825 (Dual port 8 Gbps FC)	10/31/11

This 'Certificate of Compliance' warrants that the product identified above, (and all spares, features and FRUs associated with referenced product) are manufactured in compliance with the Restriction of Hazardous Substances (RoHS), Directive 2011/65/EU. The RoHS Directive restricts the use of certain substances in electronic products; including certain allowable exemptions as noted.

☐ Allowable Exemptions:

- ☐ 6a - Lead as an alloying element in steel containing up to 0.35% lead by weight.
- ☐ 6b - Lead as an alloying element in aluminum containing up to 0.4% lead by weight.
- ☐ 6c - Lead as an alloying element in copper containing up to 4% lead by weight.
- ☑ 7a - Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).
- ☐ 7b - Lead in solders for servers, storage and storage array systems, network infrastrucutre equipment for switching, signalling, transmission as well as network management for telecommunications. This applies only to Ball Grid Array (BGA) components.
- ☑ 7cI - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
- ☐ 7cII - Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
- ☐ 7cIII - Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC.
- ☐ 7cIV - Lead in PZT (Lead Zirconate Titanate) ceramic materials for capacitors being part of integrated circuits or discrete semiconductors. Please note all other ceramic materials containing Pb used in these applications are forbidden.
- ☐ 11b - Lead used in other than C-press compliant pin connector systems
- ☑ 13a - Lead in white glass used for optical applications.
- ☐ 15 - Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Comments (if applicable): Exemption 13a applies only to products supplied with optical transceivers.

Signature (handwritten or electronic signature):

Thomas E Jones

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